PASSIVE SYSTEM ALLIANCE
Prosperity Dielectrics Co., Ltd.

Prosperity Dielectrics Co., Ltd

2026 Investor Conference

(Stock code: 6173)

Date:2026.05.21

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PSA

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- Company Profile
- Financial Performances
- Product Applications and Market Outlook
- Business Focus & Opportunity

Company Profile

Prosperity Dielectrics Corp :

- **Established** June, 1990
- **Capital** NTD 1.72 Billion
- **Employee** 735
- **Brand** PDC
- **Revenue** Y2025 NTD 4.05 Billion
  Y2026 Q1 NTD 1.02 Billion

Branch Office/ Plant :

- **Taiwan** Taoyuan / Yangmei Plant/ Tainan plant
  (expected to be completed in 2027)
- **China** Dongguan Sales Office/Logistics Center

Production experience :

- **MLCC/CR** Since 1990 (36 years)
- **Powder** Since 1995 (31 years)

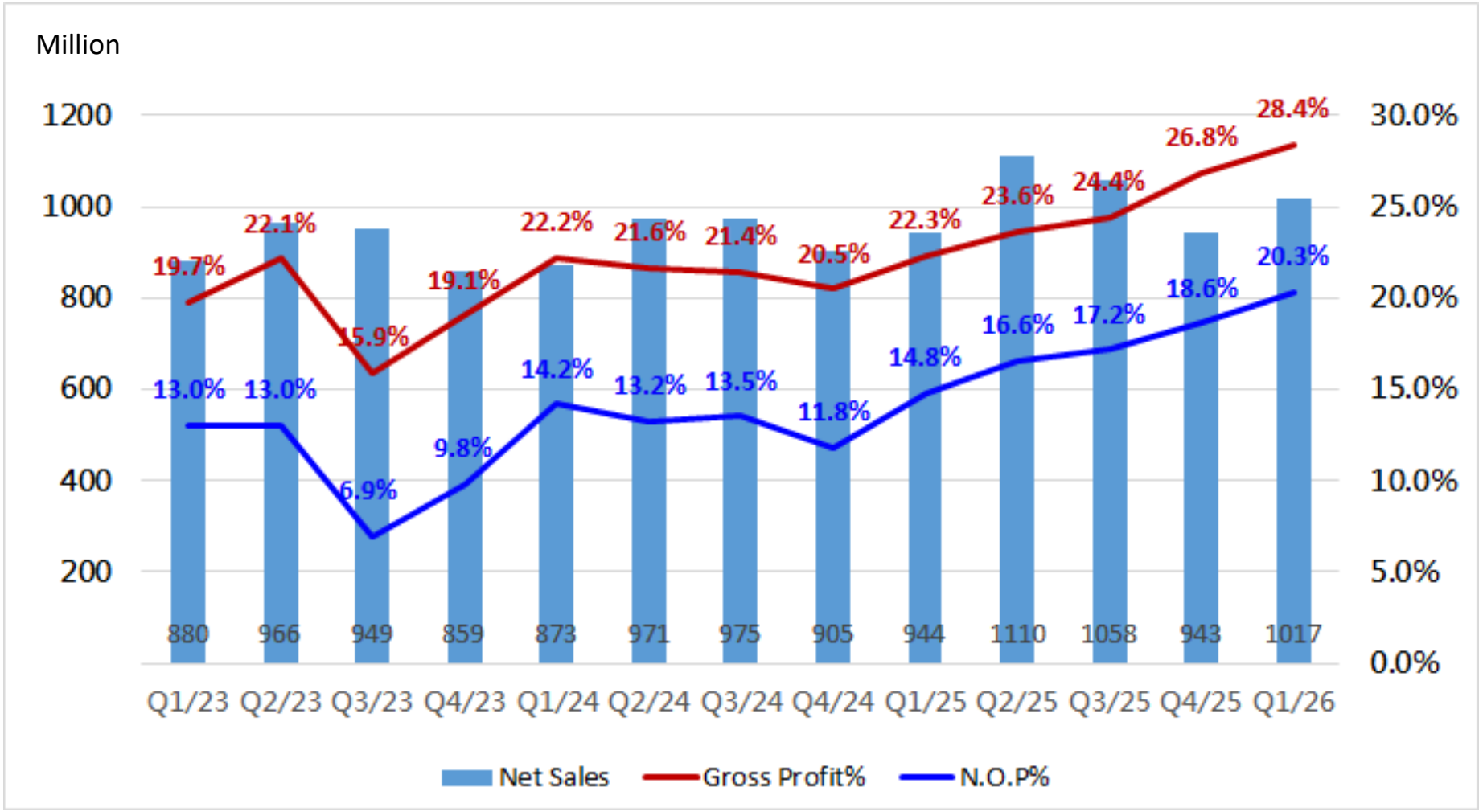
PSA

Income statement

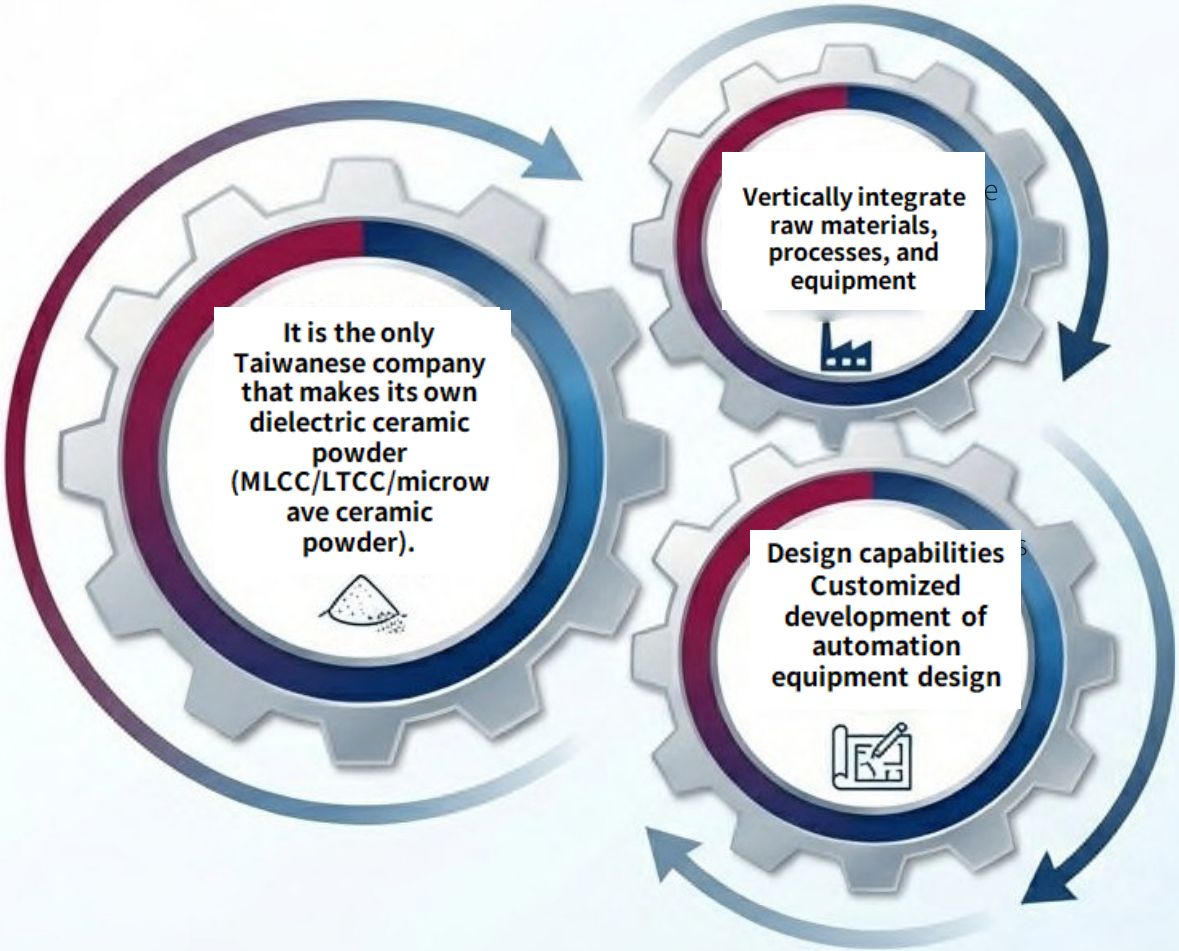
In Million NTD Except NTD for Earnings Per Share

	2026 Q1	2025 Q4	QoQ	change(%)	2025 Q1	YoY	change(%)
Net Sales	1,017	943	73	8%	944	72	8%
Gross Profit	288	253	35	14%	211	77	37%
Gross Profit(%)	28.4%	26.8%	1.5%		22.3%	6.0%	
N.O.P	207	175	31	18%	140	67	48%
N.O.P(%)	20.3%	18.6%	1.7%		14.8%	5.6%	
Income Before Tax	258	246	12	5%	153	105	69%
Net Income	205	195	10	5%	120	84	70%
Net Income(%)	20.1%	20.6%	-0.5%		12.8%	7.4%	
EPS(NTD)	1.19	1.14	0.05		0.7	0.49	

Revenue & Margin rate Trend



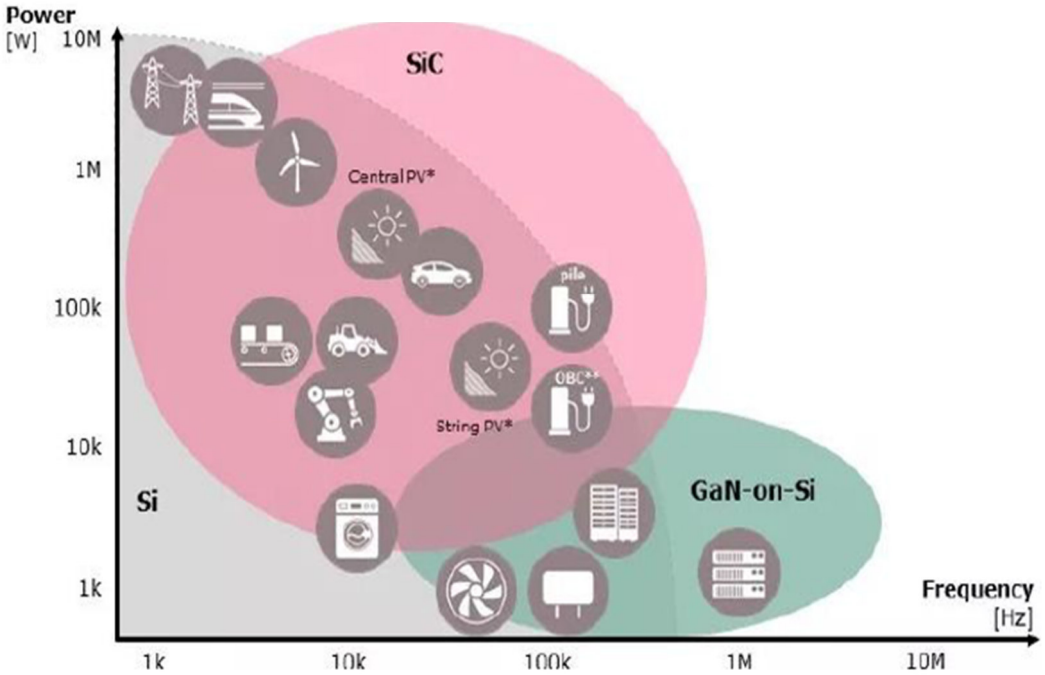
Core competitiveness



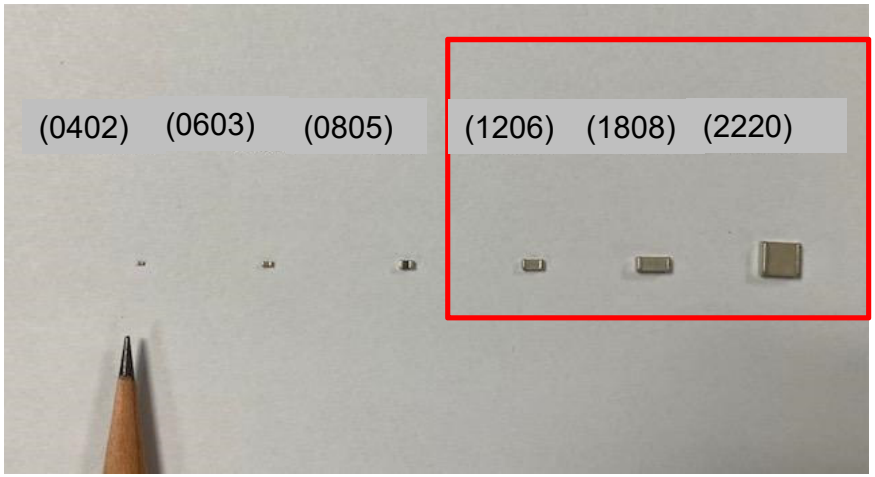
- **Supply Chain Stability:** Master the upstream Powder, not controlled by others
- **Cost Advantage:** Vertical integration optimizes production costs
- **One-Stop Shop ：** Provide one-time purchase service for capacitors, resistors, and inductors

Application Market Trends

SiC & GaN is more suitable for high voltage and high frequency applications than Si.



Source: Infineon



With the popularization and application of third-generation semiconductors (GaN, SiC), the business opportunities for large-size passive components are expanding.

Product planning and application

- 4G base station
- Server
- Modem/Router/STB
- Power supply
- Consumer electronics

- AI servers
- BBU, PD3.1 power supply
- Electric vehicles
- Industrial robots
- 5G base stations
- Medical, aerospace
- Smart grid

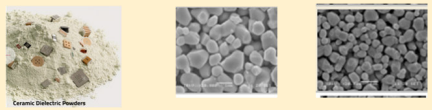
- Humanoid robot
- Self-driving car
- AI infrastructure
- AI data centers
- Low Earth Orbit Satellites
- Wireless charging for electric vehicles

2015

Operating Revenue:NT 2.39B
Gross operating margin:18.9%
EPS: 0.74

Product spindle
-Components: High power for industrial, networking, and consumer use MLCC,CHIP-R , Inductor

-Material: Disc, MLCC dielectric ceramic powder



800nm 600nm

2025

Operating Revenue:NT 4.05B
Gross operating margin:24.3%
EPS:3.26

2026 Q1

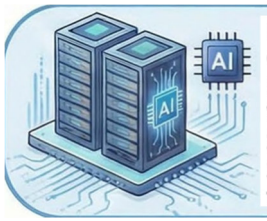
Operating Revenue:NT1.01 B
Gross operating margin:28.4%
EPS: 1.19

Product spindle
-Components: High power and high reliability for industrial, networking, automotive, medical, and aerospace applications MLCC,CHIP-R

-Materials: Disc, High Specification MLCC, LTCC, Microwave Dielectric Ceramic Powder

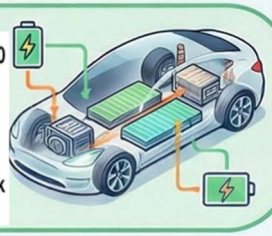
400nm 250nm 250nm 200nm

6 major application areas of PDC's high-power products



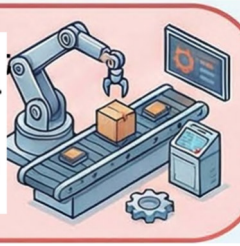
Provide the AI power cabinet needs
1 Medium and high voltage MLCC.
2 Metal Strip, FBF
3 Large size high power thick film resistor

Provide MLCCs with AEC-Q200 automotive qualification
1 Medium to high voltage MLCC
2 Metal Strip, FBF
3. Large size high-power thick film resistor



Meet the needs of 5G base stations
1 Medium and high voltage MLCCs.
2 Metal Strip, FBF
3. Large size high-power thick film resistor

Industrial Robotics & Automation1
1 Medium and high voltage MLCCs.
2 Metal Strip, FBF
3. Large size high-power thick film resistor

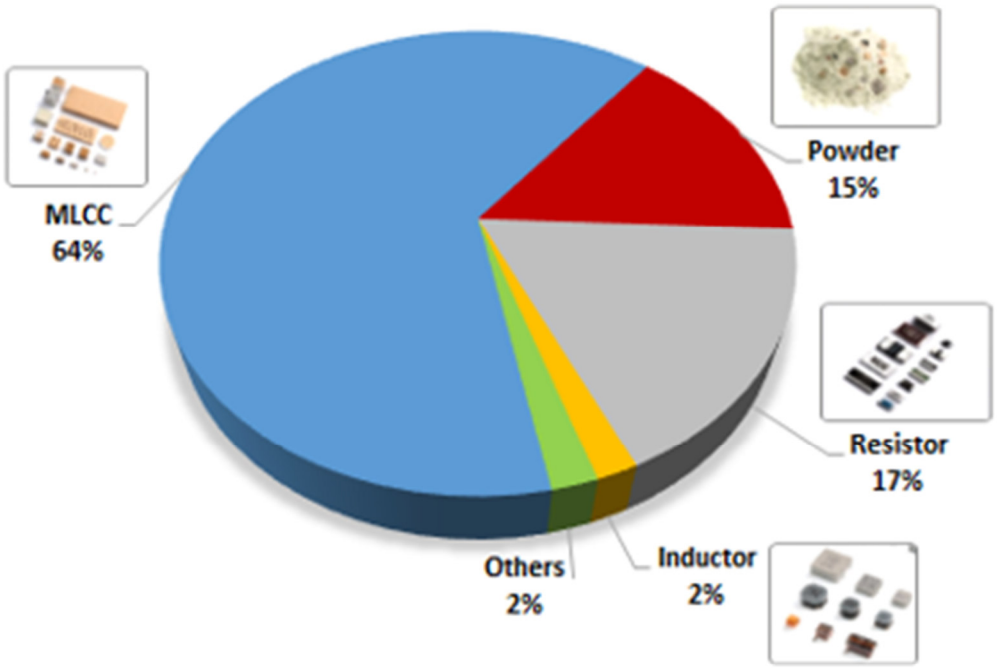


Low Earth Orbit Satellites
1 Medium and high voltage MLCCs.
2 Metal Strip, FBF
3. Large size high-power thick film resistor

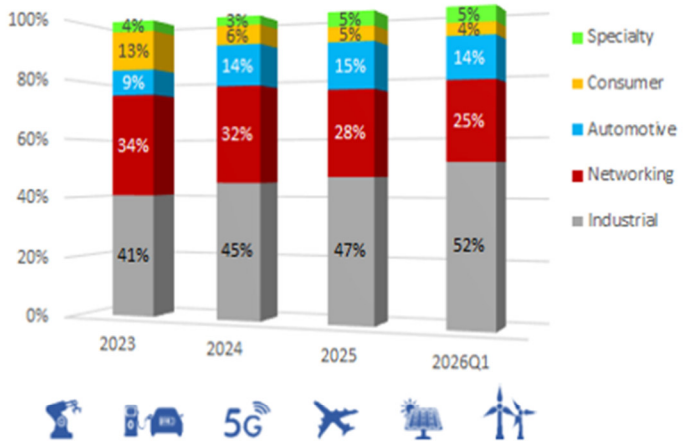
Respond to the new trend of 48V
1 Medium and high voltage MLCCs.
2 Metal Strip, FBF
3. Large size high-power thick film resistor

2026 Q1 Revenue proportion

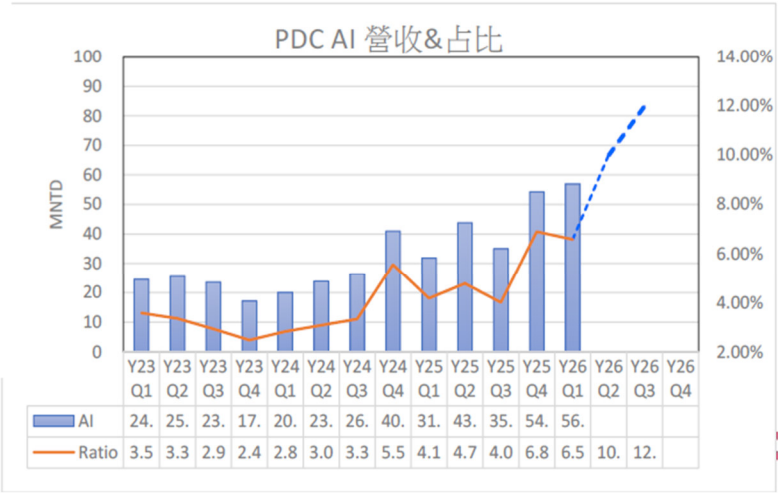
By Product



By Segment



By AI



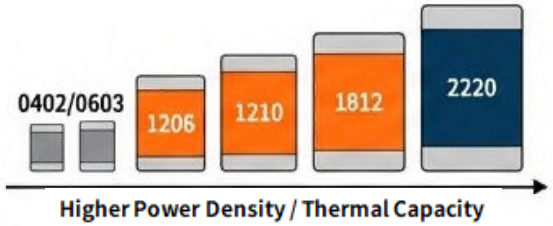
From "Consumer electronics" to "Industrial core"

The Bifurcation

The consumer goods market is saturated, but the demand for high voltage, high power, and high reliability (High-Rei) is exploding.

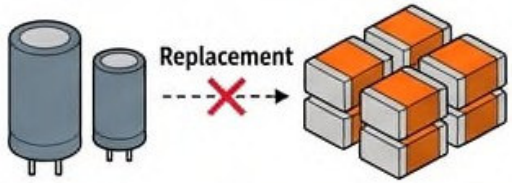
1.Size Matters:

To handle the high power density of AI and EV, capacitors need sufficient physical volume (heat capacity and withstand voltage) > = 1206/1210/1812/2220 became a key specification.



2. Replacement Cycle: Aluminum

Electrolytic capacitors and thin-film capacitors are being replaced by "large-size MLCC arrays" due to their large size and short lifespan.



Aluminum Electrolytic / Large-Size MLCC Array

Film Capacitor (Bulky, Limited Lifespan)

(Compact, Long Life, High-Rei)

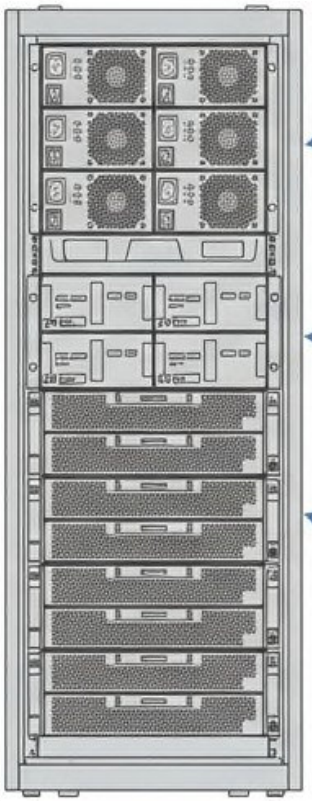
Market Growth Trend Forecast (2024-2028)

The development trend of AI server power cabinets

Paradigm Shift: From Kilowatts to Megawatts, the Power Revolution of AI Cabinets

The power consumption of a single cabinet has increased nearly 100x over several years, forcing a fundamental redesign of the power architecture. Traditional 12V power supply has reached its physical limit and cannot cope with the megawatt-level current transmission demand.

GB200 cabinet applications ≧ 1206 size high-power MLCC applications



Power supply unit(PSU)

Quantity: 1,440 -1,800 pieces

Function:HV Snubber, Resonant Tank, 48V Output Filtering

Battery backup module(BBU)

Quantity: 720 - 960 capsules

Function: 48V bidirectional filtering (especially for metal frame requirements)

Compute/Switch Trays

Quantity: 300 -1,350 pieces

Function: 48V input large capacity filtering

Total Per Rack: 3,160 ~4,210

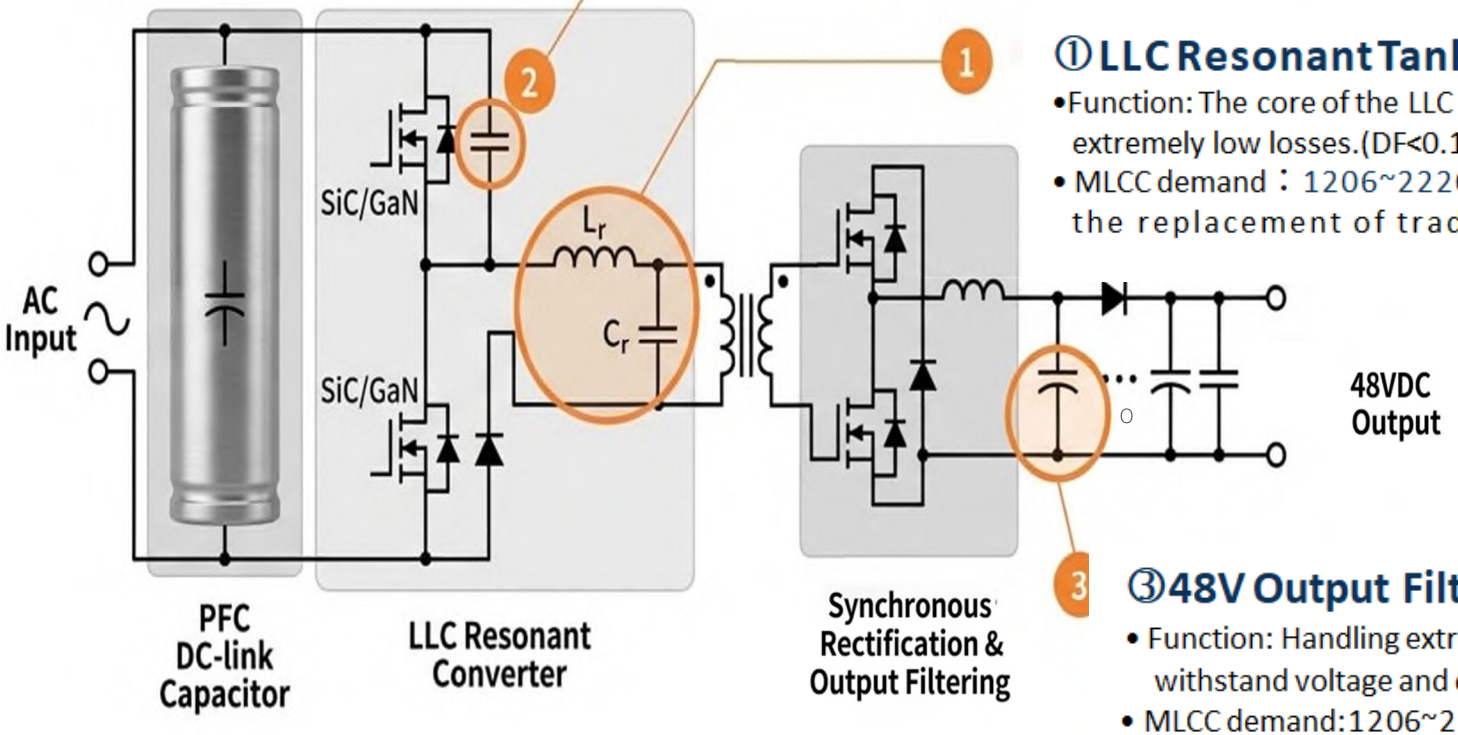
These are not ordinary products; the vast majority are high-reliability, high-capacity, and anti-brickling high-end products, with ASPs far exceeding those of consumer-grade MLCCs.

Rigorous internal challenges of the 5.5KW power supply unit (PSU)

==> PDC's MLCC offers solutions with superior performance and high reliability.

②HV Snubber Circuit

- Function:Protecting SiC/GaN power devices requires low ESL and high voltage resistance.
- MLCC demand:1206~2220, X7R/X7T, Stable capacitance and no piezoelectric noise.



①LLC Resonant Tank

- Function: The core of the LLC circuit must withstand high AC voltage and have extremely low losses.(DF<0.1%).
- MLCC demand：1206~2220,COG/630V~1000V, It is accelerating the replacement of traditional film capacitors.

③48V Output Filtering

- Function: Handling extremely high ripple current requires a 100V withstand voltage and extremely low .
- MLCC demand:1206~2220 X7S/X7R High capacitance(2.2 Uf-10uF) MLCC, used in combination with solid capacitors.

Power supply unit (PSU) 5.5KW

UL Safety Certification

Chip Size 0603 to 2512
WV 200V to 3KV
UL/IEC 62368

Metal strip CSR

Chip Size 1206 to 2512
PR 0.5W to 3W

PDC Key products ：

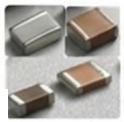
Mega Cap
(堆疊型電容)

規格：
Chip Size
1206 to 2220

Applications:
Aerospace, Medical, Military, Industrial

中高壓&高信賴性 MLCC

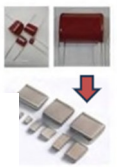
規格：
1206-2225
100V-10KV
1uFto 10uF



Applications:
Power supplies, inverters

LLCNPO電容

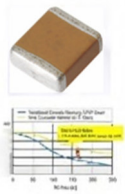
規格：1206-2220
630V~2,000V
10nFto 100nF



Features:
Replacement for film capacitors

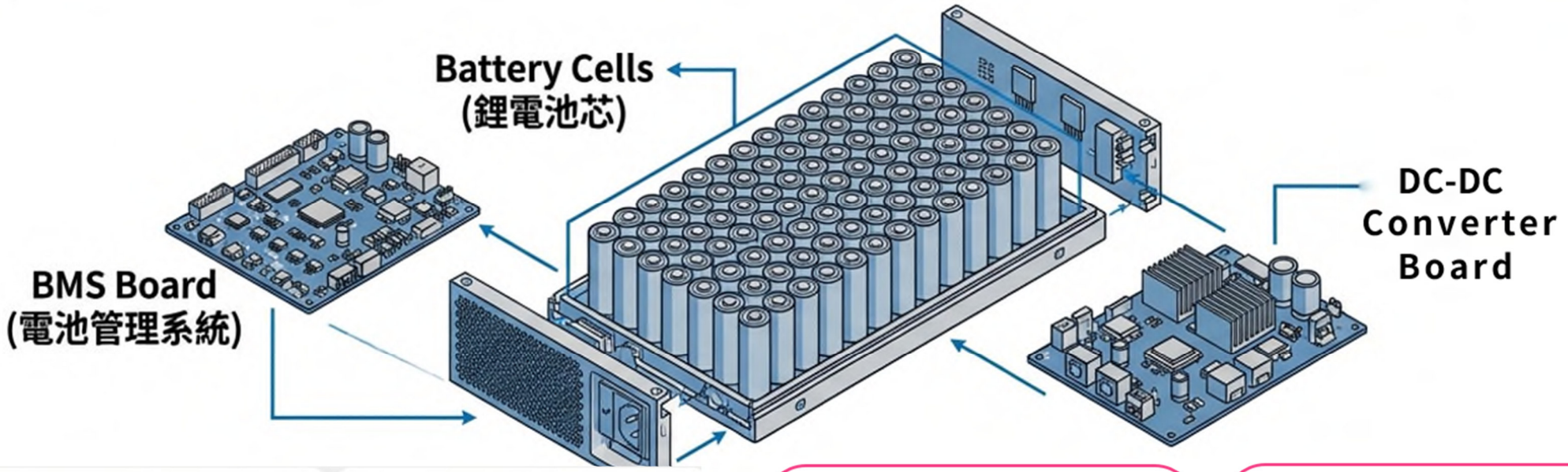
低DC BIAS電容 (X7T)

規格：
1210-2220
250V-1KV
1uFto10uF



BBU redundant battery unit

Legacy: Centralized Lead-Acid UPS → GB300:48V Rack BBU → Rubin: 800V High Voltage BBU



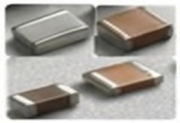
Mega Cap
(堆疊型電容)

規格：
Chip Size
1206 to 2220

Applications:
Aerospace, Medical,
Military, Industrial

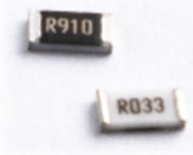
中高壓&高信賴性
MLCC

規格：
1206-2225
100V-10KV
1uFto 10uF



Applications:
Power supplies,
inverters

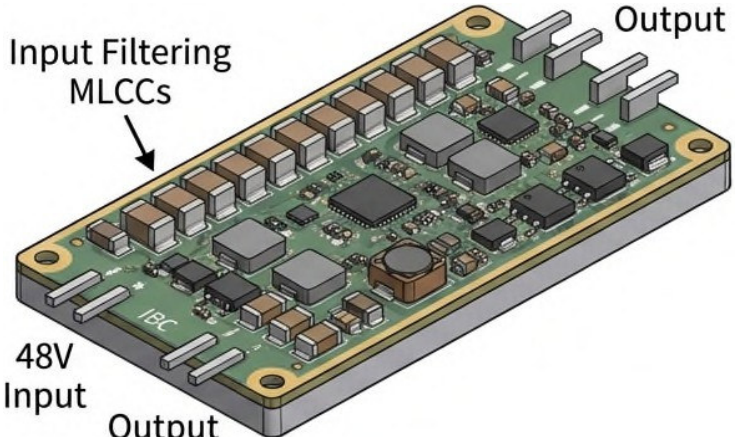
Low TCR TKF CSR
Chip Size 0603 to 2512
PR 1/8W to 2W



Anti-Surge CHR
Chip Size 0603 to 2512
PR Max 2W

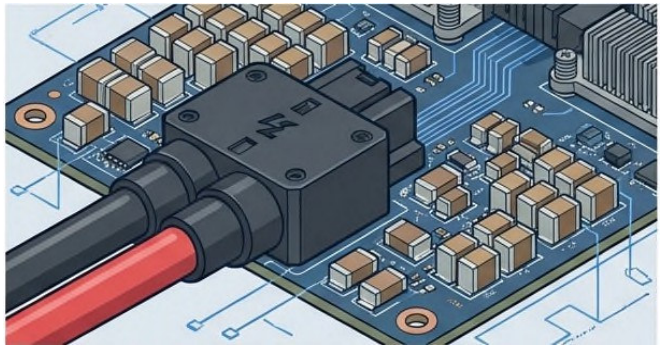
PSA

Compute tray and switch tray



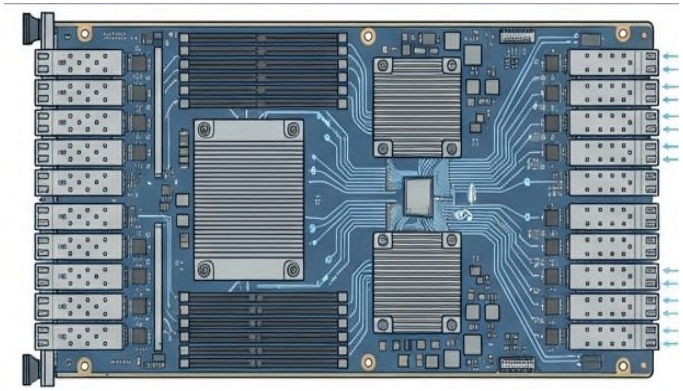
48V DC-DC and intermediate bus conversion

IBC (Intermediate Bus Converter) Even in the 800V architecture (Rubin), it is still necessary to downgrade to 48V before entering the Compute Tray, or maintain 48V distribution in GB300.



Compute Tray

- Power Entry: 48V/HVDC Input filtering.
- Snubber Circuits: Protecting VRMs from Voltage Spikes.
- MLCC Spec: A large number of 1206/1210 high-capacitance and high-reliability Capacitors are used.

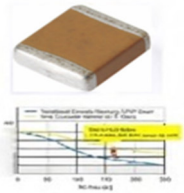


Switch Tray

- Feature: Board Flexing Risk
  Due to fan vibration and airflow，PCB is easy to deform slightly.
- MLCC Required 1206 Soft Termination products, to prevent capacitor cracking and short circuit.

低DC BIAS電容 (X7T)

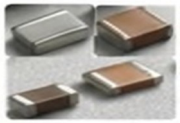
規格：
1210-2220
250V-1KV
1uFto10uF



中高壓&高信賴性 MLCC

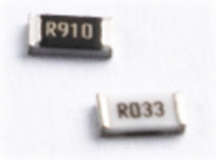
規格：
1206-2225
100V-10KV
1uFto 10uF

應用:
電源、逆變器



Low TCR TKF CSR

Chip Size 0603 to 2512
PR 1/8W to 2W



Anti-Surge CHR

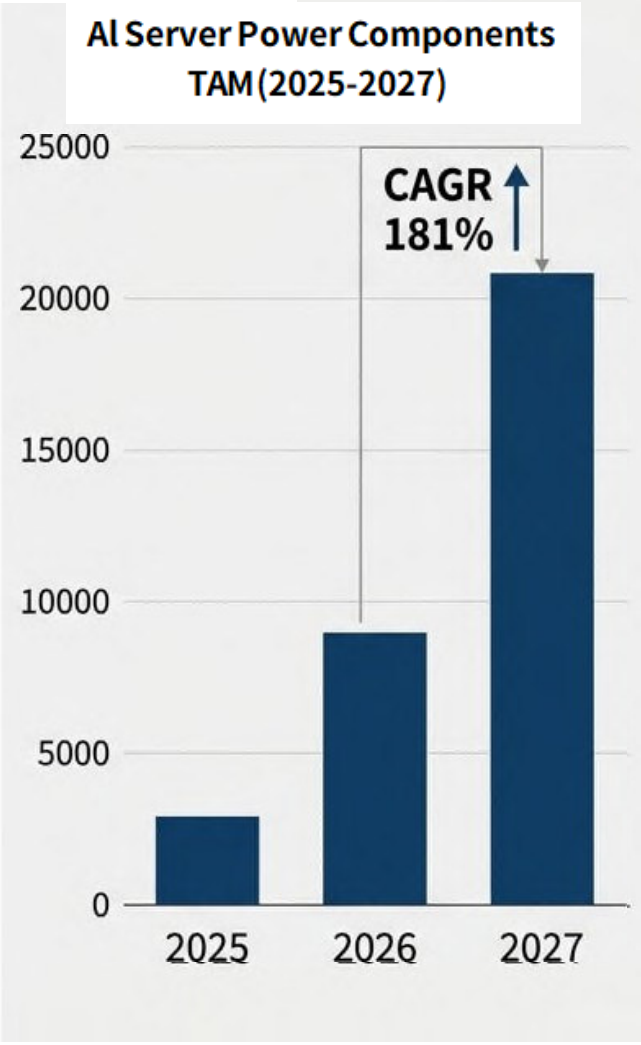
Chip Size 0603 to 2512
PR Max 2W

The high-voltage architecture drives the application of high-power MLCCs ≧ 1206 size

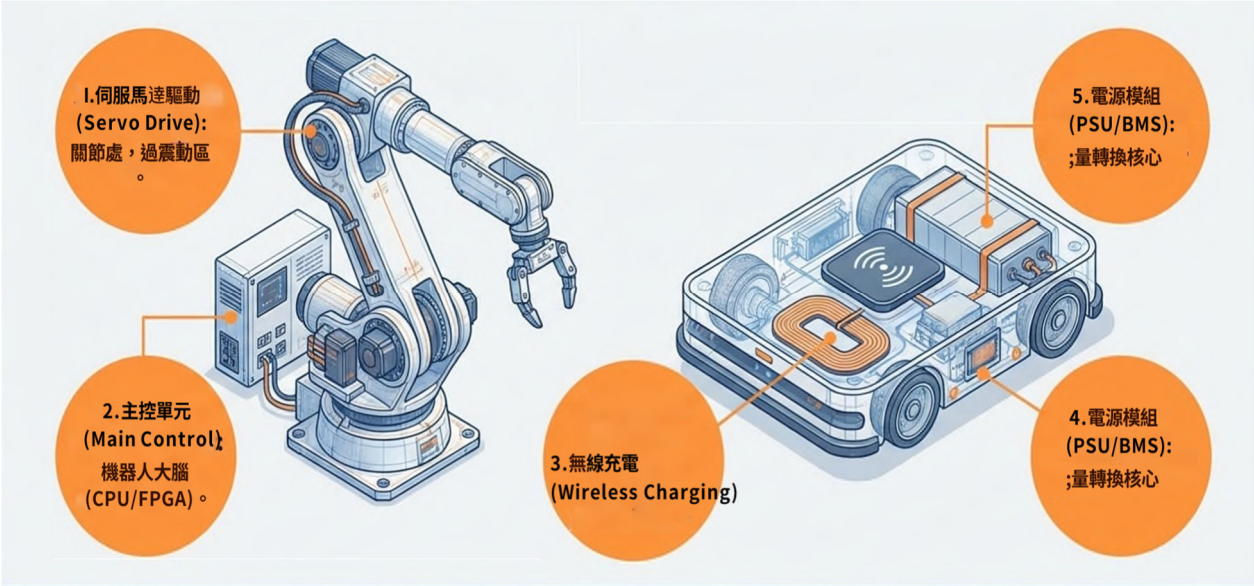
The Driver： The surge in AI computing power has driven a breakthrough in single-cabinet power consumption100kW Force the power architecture to move from traditional 12V/48V to 800V HVDC.

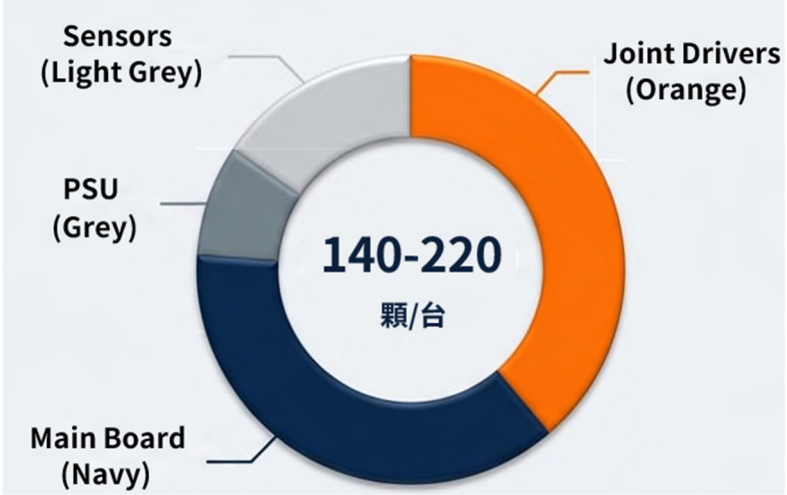
The Component：The increased voltage makes it difficult for small MLCCs (0402/0603)to withstand high pressure stress and arcing risks. For the GB300 and Rubin platforms, the power input and filter circuits require a large number of MLCCs in 1206 or even 1812/2220 size.

The Growth Spots：Key application scenarios are locked in30kW Power Shelf、BBU and 48V Conversion layer.It is estimated that the output value of power supply will increase by 181% year-on-year in 2026/2027.



Six-axis arm and VGA system in robotics applications





1. Joint Drivers: 120-180pcs (1206/1210 X7R).
2. Power supply(PSU):20~40 pcs(1812/2220 High-V X7T/X7R).

Mega Cap
(堆疊型電容)

規格：
Chip Size
1206 to 2220

Applications:
Aerospace, Medical, Military, Industrial

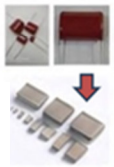
中高壓&高信賴性 MLCC

規格：
1206-2225
100V-10KV
1uFto 10uF

Applications:
Power supplies, inverters

LLCNPO電容

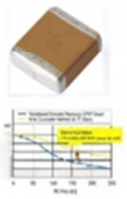
規格：1206-2220
630V~2,000V
10nFto 100nF



Features:
Replacement for film capacitors

低DC BIAS電容 (X7T)

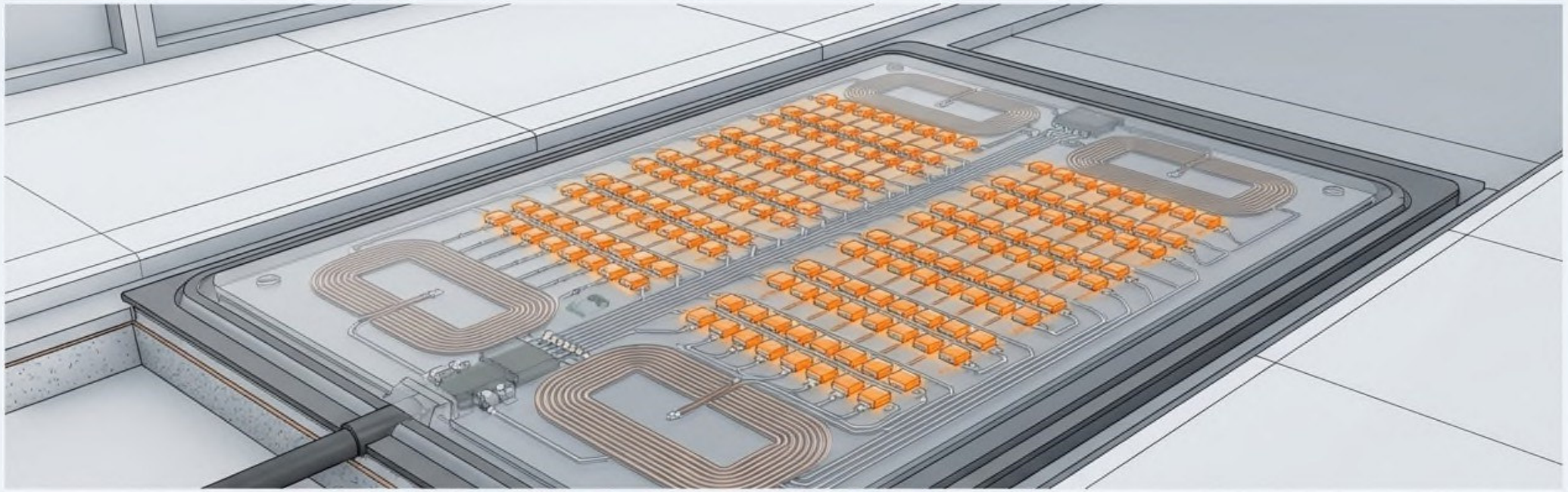
規格：
1210-2220
250V-1KV
1uFto10uF



Metal strip CSR
Chip Size 1206 to 2512
PR 0.5W to 3W

2x/3x High Power CHR
Chip Size 0603 to 2512
PR Max 3W

Wireless charging matrix in the field of humanoid robots and automotive



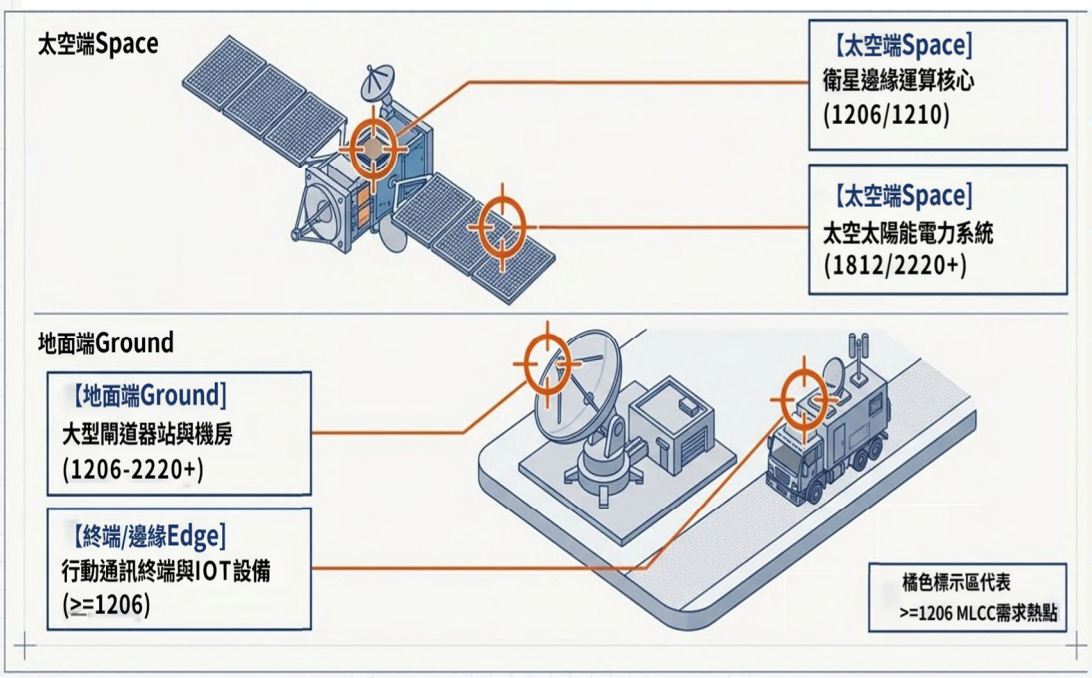
Context

- EV charging pad: 11kW (magnetic resonance technology)
- AI robot/robot dog: 500W ~ 3kW automatic recharging base
- Key Challenge: Extremely high risk of thermal runaway

Data Highlight

- EV charging pad usage: 50 ~ 200+ pcs (matrix parallel connection)
- Robot base dosage: 10 ~ 30 pcs
- Analysis: This application must use NPO (C0G) material to ensure zero thermal drift. Since a single capacitor cannot withstand the total current, customers generally adopt multiple array designs, which greatly increases the number of BOMs.

Low Earth Orbit Satellites



Equipment Areas	Main application scenarios	Recommended size	Key Features and Certifications
Ground gateway station	High-power antenna array power supply, computer room	1210~2220+	High pressure, high capacitance, extremely high stability
Satellite edge computing	Powered by the space AI processor Vcore	1206,1210	High-CV, resistant to thermal cycling
Mobile terminals	vehicle/ship/aviation communication line	>=1206	flexible terminals, earthquake resistance,AEC-Q200
Satellite IoT module	Instantaneous pulse emits backup capacitors	1206	High capacity, low ESR, and resistant to extreme weather
Satellite solar power	High voltage converters, inverters	1808~2220	200V-630V high voltage resistance

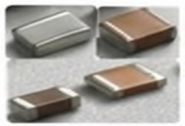
車規級電容
(Automotive Certified. Cap)

規格： AEC-Q200
X7R/NPO 1206-2220
50V-4KV

應用：
BMS, OBC,
Inverter,48V DC

中高壓&高信賴性
MLCC

規格：
1206-2225
100V-10KV
1uFto 10uF



Applications:
Power supplies,
inverters

Metal strip CSR
Chip Size 1206 to 2512
PR 0.5W to 3W

Wide Terminal CHR
Chip Size 0612 to 1225
PR 1W to 2W

5A

Industrial control and green energy

Context

- Target equipment: solar inverter (PV Inverter) & Energy storage system(ESS)
- Key requirement: ultra-high withstand voltage (Ultra-High Voltage) &Lifespan of more than 10 years

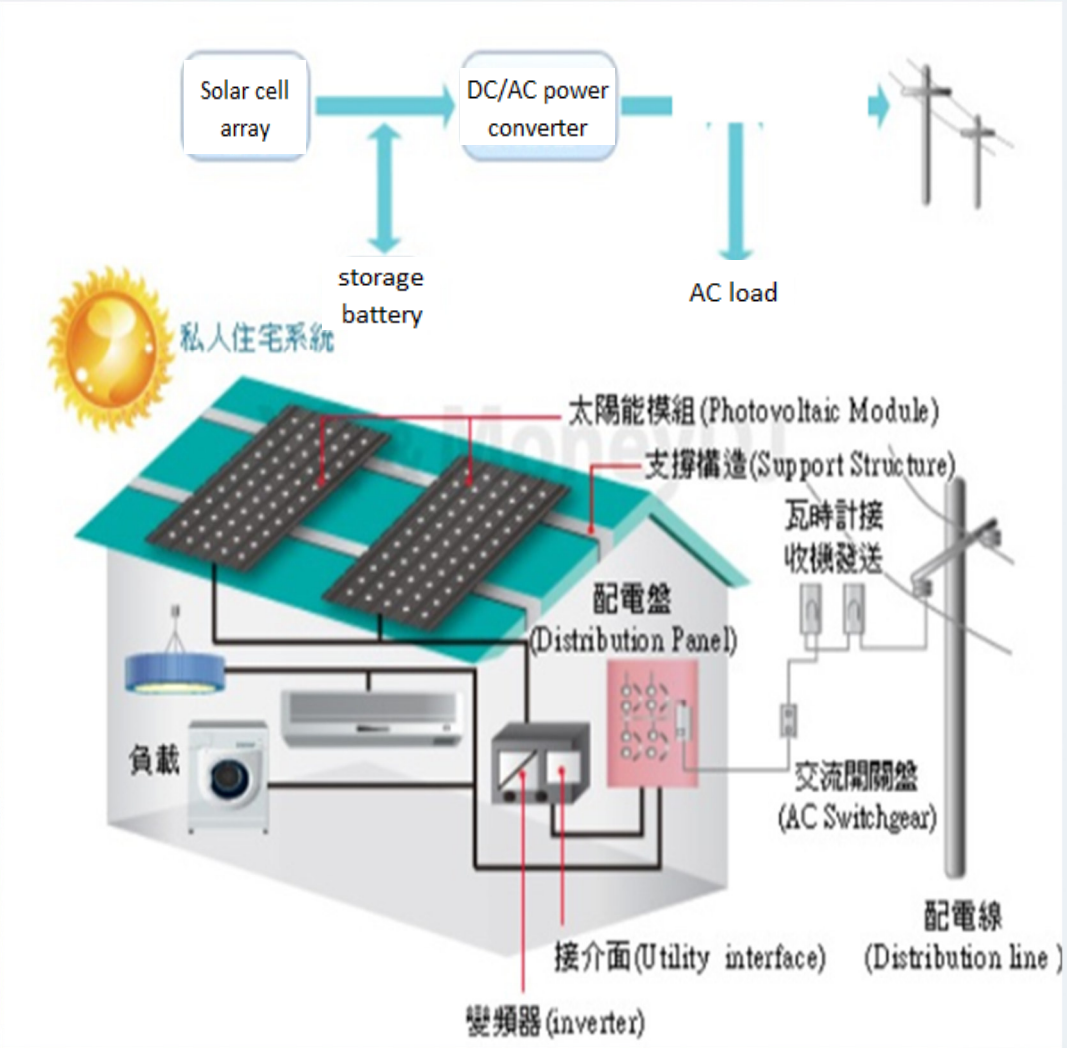
Data Highlight

Single module dosage: 30 ~ 60 pieces

Mainstream specification: 1210/1812/2220

Analysis

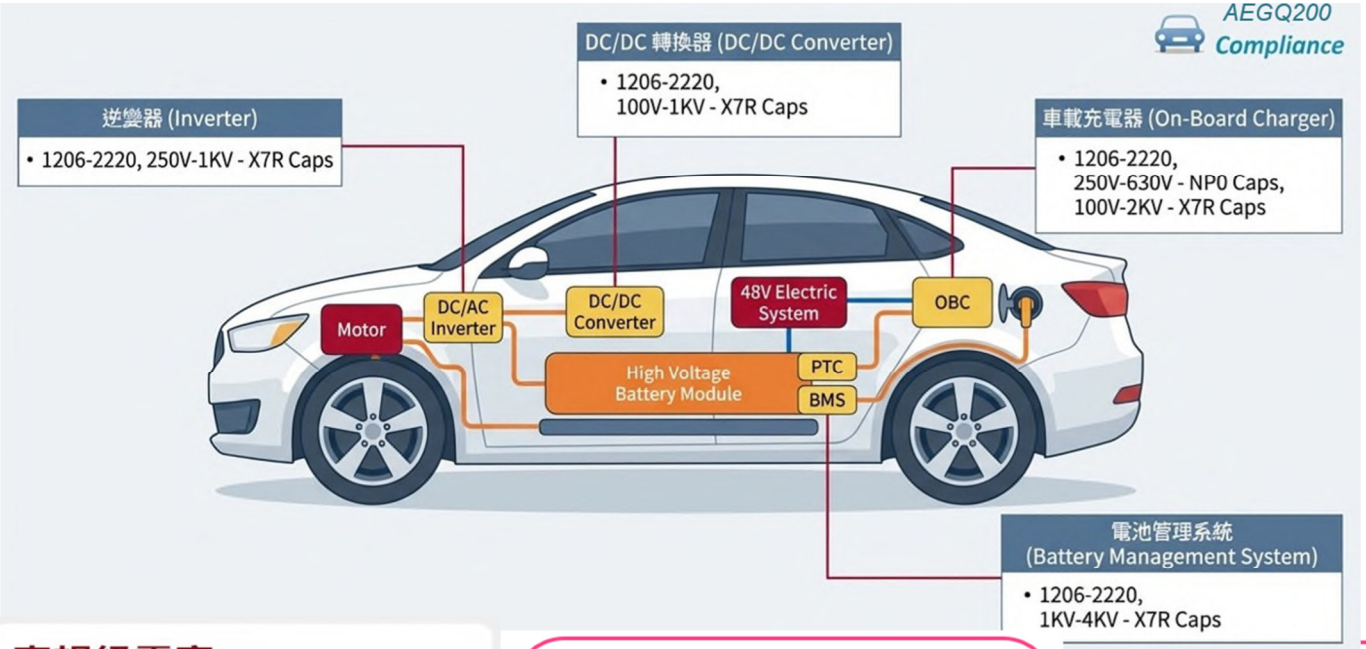
Unlike consumer electronics, this field requires a withstand voltage rating of 2kV ~ 3kV. Large-format MLCCs offer better surface mount (SMT) production efficiency and long-term reliability than thin-film capacitors.



Electric vehicle(EV)

A Collection of Challenges:

High temperatures, violent vibrations, high voltage electricity, and absolute safety that are at stake for human life.



A huge shift is taking place: from 400V to 800V

The mainstream electric vehicle voltage platform is now 400V, but the entire industry is moving towards 800V or even higher.

- Advantages: more Fast charging speed, lower energy loss.
- Cost: The insulation ability, heat resistance, and physical limits of each basic component are tested like never before. It is the revolution of the entire industry chain from materials to processes.

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Metal strip CSR

Chip Size 1206 to 2512
PR 0.5W to 3W

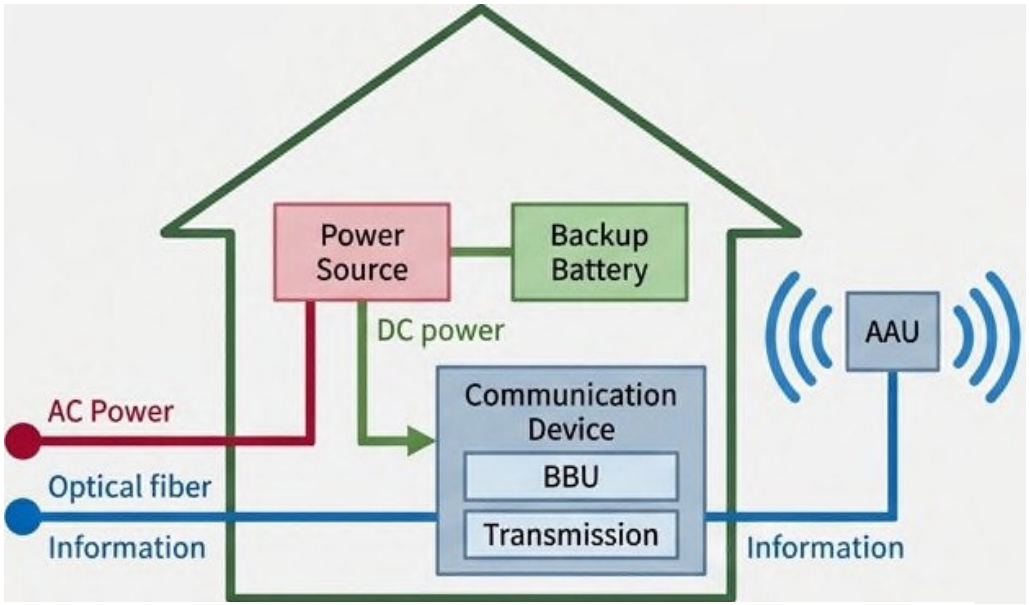
Wide Terminal CHR

Chip Size 0612 to 1225
PR 1W to 2W

Anti-Surge CHR

Chip Size 0603 to 2512
PR Max 2W

5G base station solutions



Application Challenges

5G base stations have the characteristics of high speed, high frequency, high power consumption and high heat, and are proposed to MLCCs with high temperature resistance, low loss (Low DF) and excellence Requirements for DC bias characteristics (Good DC-Bias).

PDC Key products
MLCC

- High-temperature, low-loss products : FM55T224K631/ FM55T474KG31 (2220 X7T 630V)
- Excellent DC offset seat characteristic products : FS31X225K101 / FS32X475K101 (X7R 100V)
- High capacity products: FS32X22GK250 (1210 X7R 22uF 25V)

中高壓&高信賴性 MLCC

規格：
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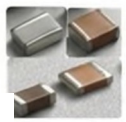
100V-10KV
1uFto 10uF

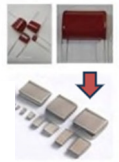
Applications:
Power supplies, inverters



LLCNPO電容

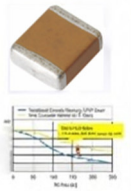
規格： 1206-2220
630V~2,000V
10nFto 100nF

Features:
Replacement for film capacitors



低DC BIAS電容 (X7T)

規格：
1210-2220
250V-1KV
1uFto10uF



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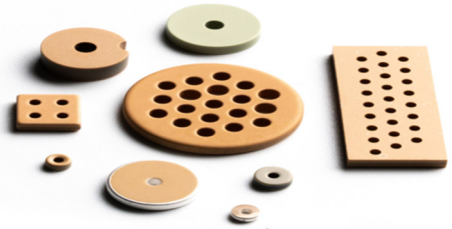
PDC core -MLCC technology portfolio

Mega Cap
(Stacked capacitors)

Specifications：
Chip Size
1206 to 2220

Application：
Aerospace, medical, military, industrial
High vibration and mechanical stress environments

Discoidal Cap



Application:
Aerospace, medical, military, industrial

LLC NPO MLCC

Specifications：
1206-2220
630V~2,000V
10nFto 100nF

Features:
Replace thin-film capacitors

Medium and high voltage MLCC

Specifications：
1206-2225
100V~10KV
1uF to 10uF

Application:
Power supply, inverter

Safety capacitors
(Safety Certified Cap)

Specifications：
X1/Y2,X2/Y3
1206-2220
3000V/5000V

Applications:
Power EMI filtering

Automotive-grade capacitors

Specifications：
AEC-Q200 X7R/NPO 1206-2220
50V-4KV

Application：
BMS, OBC, Inverter,48V DC

Low DC BIAS Cap(X7T)

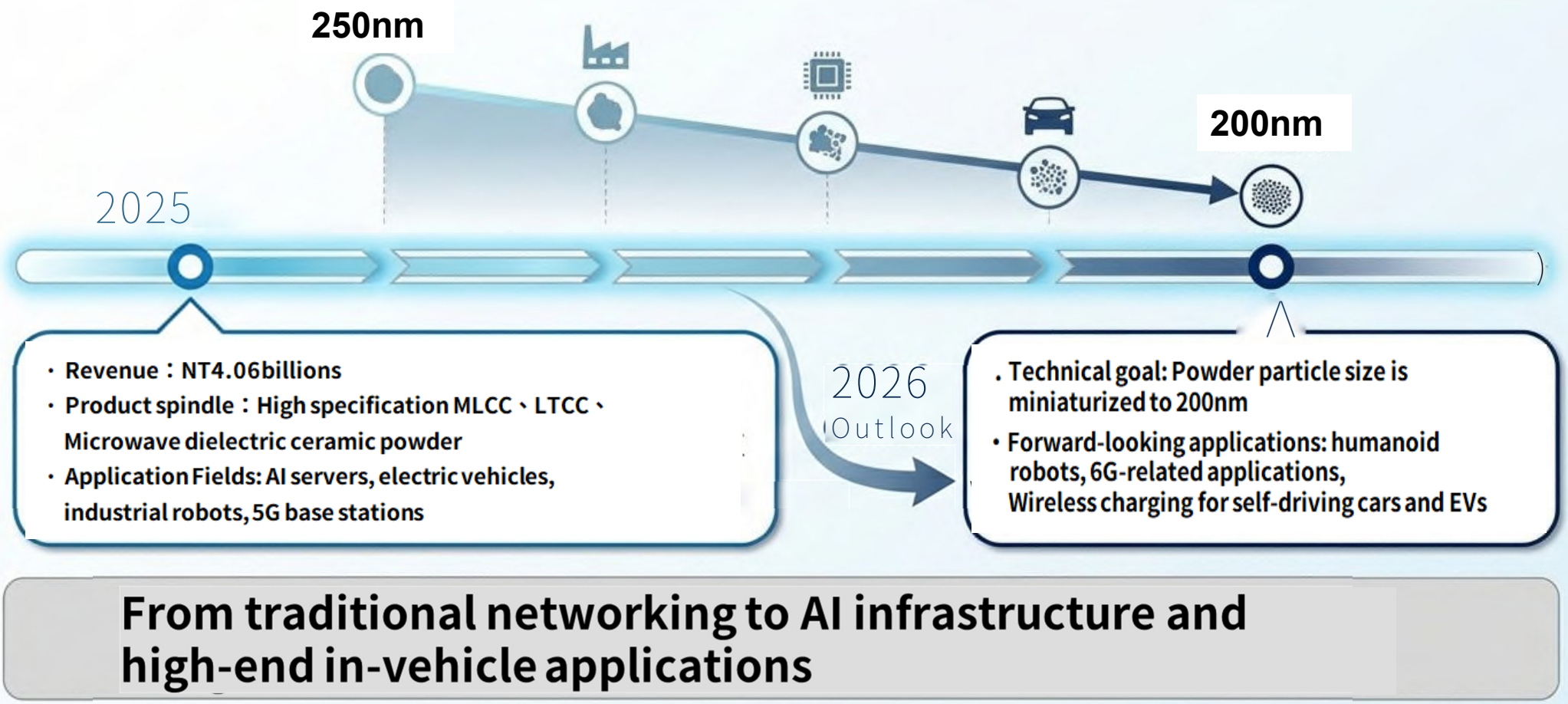
Specifications：
1210-2220
250V~ 1KV
1uF to 10uF

High power/surge resistance

Specifications：
0603 to 2512 PR Max 3W

Applications:
Power protection, power regulation

MLCC Core Material Development Blueprint



From traditional networking to AI infrastructure and high-end in-vehicle applications

Opportunity

- With the rapid growth of AI server power cabinets, data centers, and new energy vehicles, as well as the expected demand for low-orbit satellites and humanoid robots in the future, the demand for PDC's main high-power and large-size products has increased significantly.
- With the popularization of GaN and SiC semiconductors, the power demand rate of end products has increased, which has greatly increased the demand for SMD high-power and high-reliability passive components.
- High-reliability NPO MLCCs replace Film Caps and X7R, and X7T MLCCs replace aluminum and tantalum electrolytic capacitors, and their applications will increase significantly.
- The large increase in related RF components for 5G applications has led to an increase in the demand for ceramic powders for LTCC and high-frequency low-dielectric filtering applications.

PSA

Business focus

■ MLCC、 Chip-R

- For high-growth application market areas, we continue to develop high-power and high-capacitance MLCCs and high-power chip-R.
- With independent material development and process technology capabilities, it can effectively cooperate with medium and high voltage and large-size special MLCCs to introduce high value-added markets, and reduce costs to enhance competitiveness.

■ Dielectric ceramic powder

- Continue to develop high-end, high-temperature, high-voltage, high-capacity, and special application MLCC dielectric ceramic powder.
- In response to the growing market demand for 5G and AI applications, we continue to develop microwave powders for high-end and special applications.
- Continue to develop various series of LTCC materials for RF/high-frequency components and Cu electrode process MLCC dielectric ceramic powder.

Thank you!